## The SN54F299 is obsolete and no longer supplied.

- Four Modes of Operation:
- Hold (Store)
- Shift Right
- Shift Left
- Load Data
- Operates With Outputs Enabled or at High Impedance
- 3-State Outputs Drive Bus Lines Directly
- Can Be Cascaded for N-Bit Word Lengths
- Direct Overriding Clear
- Applications:
- Stacked or Pushdown Registers
- Buffer Storage
- Accumulator Registers


## description/ordering information

These 8 -bit universal shift/storage registers feature multiplexed I/O ports to achieve full 8-bit data handling in a single 20 -pin package. Two function-select (S0, S1) inputs and two output-enable ( $\overline{\mathrm{OE} 1,} \overline{\mathrm{OE} 2}$ ) inputs can be used to choose the modes of operation listed in the function table.

Synchronous parallel loading is accomplished by taking both S0 and S1 high. This places the 3 -state outputs in a high-impedance state and permits data that is applied on the I/O ports to be clocked into the register. Reading out of the register can be accomplished while the outputs are enabled in any mode. Clearing occurs when the clear ( $\overline{\mathrm{CLR})}$ input is low. Taking either $\overline{\mathrm{OE}}$ or $\overline{\mathrm{OE} 2}$ high disables the outputs but has no effect on clearing, shifting, or storage of data.

## ORDERING INFORMATION

| $T_{A}$ | PACKAGE $\dagger$ |  | ORDERABLE <br> PART NUMBER | TOP-SIDE <br> MARKING |
| :--- | :--- | :--- | :--- | :--- |
|  | PDIP - N | Tube of 20 | SN74F299N | SN74F299N |
|  | SOIC - DW | Tube of 25 | SN74F299DW | F299 |
|  |  | SN74F299DWR |  |  |
|  | SOP - NS | Reel of 2000 | SN74F299NSR | $74 F 299$ |

$\dagger$ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.


SN54F299... FK PACKAGE (TOP VIEW)


FUNCTION TABLE

| MODE | INPUTS |  |  |  |  |  |  |  | I/O PORTS |  |  |  |  |  |  |  | OUTPUTS |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | $\overline{\text { CLR }}$ | S1 | So | $\overline{\mathrm{OE}} \dagger$ | $\overline{\mathrm{OE} 2} \dagger$ | CLK | SL | SR | $\mathrm{A}^{\prime} \mathrm{Q}_{\mathbf{A}}$ | $B / Q_{B}$ | $\mathrm{C} / \mathrm{Q}_{\mathrm{C}}$ | $D / Q_{D}$ | $E / Q_{E}$ | F/Q ${ }_{\text {F }}$ | $\mathrm{G} / \mathrm{Q}_{\mathrm{G}}$ | H/Q $\mathrm{Q}_{\mathrm{H}}$ | $Q_{\mathbf{A}^{\prime}}$ | $\mathrm{Q}_{\mathbf{H}^{\prime}}$ |
| Clear | L | X | L | L | L | X | X | X | L | L | L | L | L | L | L | L | L | L |
|  | L | L | X | L | L | X | X | X | L | L | L | L | L | L | L | L | L |  |
|  | L | H | H | X | X | X | X | X | X | X | X | X | X | X | X | X | L | L |
| Hold | H | L | L | L | L | X | X | X | $\mathrm{Q}_{\text {A0 }}$ | QB0 | Q ${ }_{\text {co }}$ | QD0 | QE0 | QF0 | QG0 | Qно | QA0 | QH0 |
|  | H | X | X | L | L | L | X | X | QA0 | QB0 | Q ${ }_{\text {C0 }}$ | $Q_{\text {D0 }}$ | QE0 | QF0 | $Q_{G 0}$ | QH0 | QA0 | QH0 |
| Shift | H | L | H | L | L | $\uparrow$ | X | H | H | $Q_{\text {An }}$ | $\mathrm{Q}_{\mathrm{Bn}}$ | $Q_{\text {Cn }}$ | QDn | QEn | QFn | $Q_{G n}$ | H | $Q_{G n}$ |
| Right | H | L | H | L | L | $\uparrow$ | X | L | L | $Q_{\text {An }}$ | $Q_{B n}$ | $Q_{C n}$ | Q ${ }_{\text {Dn }}$ | QEn | $Q_{\text {Fn }}$ | $Q_{G n}$ | L | $Q_{G n}$ |
| Shift | H | H | L | L | L | $\uparrow$ | H | X | QBn | $Q_{C n}$ | QDn | $Q_{\text {En }}$ | QFn | $Q_{G n}$ | $\mathrm{Q}_{\mathrm{Hn}}$ | H | Q ${ }_{\text {Bn }}$ | H |
| Left | H | H | L | L | L | $\uparrow$ | L | X | QBn | $Q_{C n}$ | QDn | QEn | $\mathrm{Q}_{\mathrm{Fn}}$ | $Q_{G n}$ | QHn | L | QBn | L |
| Load | H | H | H | X | X | $\uparrow$ | X | X | a | b | c | d | e | f | g | h | a | h |

NOTE: a . . $\mathrm{h}=$ the level of the steady-state input at inputs A through H , respectively. This data is loaded into the flip-flops while the flip-flop outputs are isolated from the I/O terminals.
$\dagger$ When one or both output-enable inputs are high, the eight I/O terminals are disabled to the high-impedance state; however, sequential operation or clearing of the register is not affected.

## logic diagram (positive logic)




## absolute maximum ratings over operating free-air temperature range (unless otherwise noted) $\dagger$

| Supply voltage range, ${ }^{\text {CC }}$ | -0.5 V to 7 V |
| :---: | :---: |
| Input voltage range, $\mathrm{V}_{\mathrm{I}}$ (see Note 1) | -1.2 V to 7 V |
| Input current range | -30 mA to 5 mA |
| Voltage range applied to any output in the disabled or power-off state | 0.5 V to 5.5 V |
| Voltage range applied to any output in the high state | -0.5 V to $\mathrm{V}_{\mathrm{CC}}$ |
| Current into any output in the low state: $\mathrm{Q}_{\mathrm{A}^{\prime}}$ or $\mathrm{Q}_{\mathrm{H}^{\prime}}$ | 40 mA |
| SN54F299 ( $\mathrm{Q}_{\text {A }}$ thru $\mathrm{Q}_{\mathrm{H}}$ ) | 0 mA |
| SN74F299 ( $\mathrm{Q}_{\text {A }}$ thru $\mathrm{Q}_{\mathrm{H}}$ ) | 48 mA |
| Package thermal impedance, $\theta_{\text {JA }}$ (see Note 2): DW package | $58^{\circ} \mathrm{C} / \mathrm{W}$ |
| N package | $69^{\circ} \mathrm{C} / \mathrm{W}$ |
| NS package | $60^{\circ} \mathrm{C} / \mathrm{W}$ |
| Storage temperature range, $\mathrm{T}_{\text {stg }}$ | $65^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$ |
| esses beyond those listed under "absolute maximum ratings" may cause permanent dama ctional operation of the device at these or any other conditions beyond those indicated plied. Exposure to absolute-maximum-rated conditions for extended periods may affect der | ess ratings only, and ng conditions" is not |
| ES: 1. The input voltage ratings may be exceeded provided the input current ratings a |  |
| 2. The package thermal impedance is calculated in accordance with JESD 51-7. |  |

recommended operating conditions (see Note 3)

|  |  |  | SN54F299 |  |  | SN74F299 |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | MIN | NOM | MAX | MIN | NOM | MAX |  |
| $\mathrm{V}_{\mathrm{CC}}$ | Supply voltage |  | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| $\mathrm{V}_{\text {IH }}$ | High-level input voltage |  | 2 |  |  | 2 |  |  | V |
| $\mathrm{V}_{\text {IL }}$ | Low-level input voltage |  |  |  | 0.8 |  |  | 0.8 | V |
| IIK | Input clamp current |  |  |  | -18 |  |  | -18 | mA |
|  |  | $\mathrm{Q}_{\mathrm{A}^{\prime}}$ or $\mathrm{Q}_{H^{\prime}}$ |  |  | -1 |  |  | -1 | mA |
| OH | h-level output current | $Q_{A}$ thru $Q_{H}$ |  |  | -3 |  |  | -3 |  |
| ${ }^{\text {IOL}}$ | Low-level output current | $Q_{A^{\prime}}$ or $Q_{H^{\prime}}$ |  |  | 20 |  |  | 20 | mA |
|  |  | $Q_{A}$ thru $Q_{H}$ |  |  | 20 |  |  | 24 |  |
| $\mathrm{T}_{\mathrm{A}}$ | Operating free-air temperature |  | -55 |  | 125 | 0 |  | 70 | ${ }^{\circ} \mathrm{C}$ |

NOTE 3: All unused inputs of the device must be held at $\mathrm{V}_{\mathrm{CC}}$ or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER |  | TEST CONDITIONS |  | SN54F299 |  | SN74F299 |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | MIN | TYPt MAX | MIN | TYP† MAX |  |
| $\mathrm{V}_{\mathrm{IK}}$ |  |  |  | $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$, | $\mathrm{I}_{\mathrm{I}}=-18 \mathrm{~mA}$ |  | -1.2 |  | -1.2 | V |
| V OH | $\mathrm{Q}_{\mathrm{A}^{\prime}}$ or $\mathrm{Q}_{H^{\prime}}$ | $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ | $\mathrm{I} \mathrm{OH}=-1 \mathrm{~mA}$ | 2.5 | 3.4 | 2.5 | 3.4 | V |
|  | $Q_{A}$ thru $Q_{H}$ |  | $\mathrm{I}^{\mathrm{OH}}=-1 \mathrm{~mA}$ | 2.5 | 3.4 | 2.5 | 3.4 |  |
|  |  |  | $\mathrm{I} \mathrm{OH}=-3 \mathrm{~mA}$ | 2.4 | 3.3 | 2.4 | 3.3 |  |
|  | Any output | $\mathrm{V}_{\mathrm{CC}}=4.75 \mathrm{~V}$, | $\mathrm{I} \mathrm{OH}=-1 \mathrm{~mA}$ to -3 mA |  |  | 2.7 |  |  |
| VOL | $\mathrm{Q}_{\mathrm{A}^{\prime}}$ or $\mathrm{Q}_{\mathrm{H}^{\prime}}$ | $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ | $\mathrm{IOL}=20 \mathrm{~mA}$ |  | 0.300 .5 |  | 0.30 .5 | V |
|  | QA thru $\mathrm{QH}_{\text {H }}$ |  | $\mathrm{IOL}=20 \mathrm{~mA}$ |  | $0.3-0.5$ |  |  |  |
|  |  |  | $\mathrm{l} \mathrm{OL}=24 \mathrm{~mA}$ |  |  |  | $0.35 \quad 0.5$ |  |
| 1 | A thru H | $\mathrm{V}_{\mathrm{CC}}=5.5 \mathrm{~V}$ | $\mathrm{V}_{\mathrm{I}}=5.5 \mathrm{~V}$ |  | 1 |  | 1 | mA |
|  | Any other |  | $\mathrm{V}_{\mathrm{I}}=7 \mathrm{~V}$ |  | 0.1 |  | 0.1 |  |
| ${ }_{11}{ }^{\ddagger}$ | A thru H | $\mathrm{V}_{\mathrm{CC}}=5.5 \mathrm{~V}$, | $\mathrm{V}_{\mathrm{I}}=2.7 \mathrm{~V}$ |  | 70 |  | 70 | $\mu \mathrm{A}$ |
|  | Any other |  |  |  | 20 |  | 20 |  |
| ${ }_{1 / 2}{ }^{\ddagger}$ | A thru H | $\mathrm{V}_{\mathrm{CC}}=5.5 \mathrm{~V}$, | $\mathrm{V}_{\mathrm{I}}=0.5 \mathrm{~V}$ |  | -0.65 |  | -0.65 | mA |
|  | S0 or S1 |  |  |  | -1.2 |  | -1.2 |  |
|  | Any other |  |  |  | -0.6 |  | -0.6 |  |
| los§ |  | $\mathrm{V}_{\mathrm{CC}}=5.5 \mathrm{~V}$, | $\mathrm{V}_{\mathrm{O}}=0$ | -60 | -150 | -60 | -150 | mA |
| ICC |  | $\mathrm{V}_{\mathrm{CC}}=5.5 \mathrm{~V}$, | See Note 4 |  | $68 \quad 95$ |  | $68 \quad 95$ | mA |

$\dagger$ All typical values are at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.
$\ddagger$ For I/O ports ( $Q_{A}$ thru $\left.Q_{H}\right)$, the parameters $\mathrm{l}_{\mathrm{IH}}$ and $\mathrm{I}_{\mathrm{IL}}$ include the off-state output current.
$\S$ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.
NOTE 4: ICC is measured with $\overline{\mathrm{OE} 1}, \overline{\mathrm{OE} 2}$, and CLK at 4.5 V .
timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)


TI Inactive-state setup time also is referred to as recovery time.
switching characteristics (see Figure 1)

| PARAMETER | FROM (INPUT) | то (OUTPUT) | $\begin{gathered} \mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \\ \mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}, \\ \mathrm{R}_{\mathrm{L}}=500 \Omega, \\ \mathrm{~T}_{\mathbf{A}}=25^{\circ} \mathrm{C} \\ \hline \text { ' } \mathrm{F} 299 \end{gathered}$ |  |  | $\begin{aligned} & \mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V} \text { to } 5.5 \mathrm{~V}, \\ & \mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}, \\ & \mathrm{R}_{\mathrm{L}}=500 \Omega, \\ & \mathrm{~T}_{\mathrm{A}}=\operatorname{MIN} \text { to MAX } \dagger \end{aligned}$ |  |  |  | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  |  |  | SN54F299 |  | SN74F299 |  |  |
|  |  |  | MIN | TYP | MAX | MIN | MAX | MIN | MAX |  |
| ${ }_{\text {max }}$ |  |  | 70 | 100 |  | 65 |  | 70 |  | MHz |
| tPLH | CLK | $\mathrm{Q}_{\mathrm{A}^{\prime}}$ or $\mathrm{QH}^{\prime}$ | 3.2 | 6.6 | 9 | 2.7 | 10.5 | 3.2 | 10 | ns |
| tPHL |  |  | 2.7 | 6.1 | 8.5 | 2.2 | 10 | 2.7 | 9.5 |  |
| tPLH | CLK | $Q_{A}$ thru $Q_{H}$ | 3.2 | 6.6 | 9 | 2.7 | 11 | 3.2 | 10 | ns |
| tPHL |  |  | 4.2 | 8.1 | 11 | 3.7 | 12.5 | 4.2 | 12 |  |
| tPHL | $\overline{C L R}$ | $\mathrm{Q}_{\mathrm{A}^{\prime}}$ or $\mathrm{Q}_{\mathrm{H}^{\prime}}$ | 3.7 | 7.1 | 9.5 | 3.2 | 11.5 | 3.7 | 10.5 | ns |
|  |  | $Q_{A}$ thru $Q_{H}$ | 5.7 | 10.6 | 14 | 5 | 15.5 | 5.7 | 15 |  |
| tPZH | $\overline{\mathrm{OE} 1}$ or $\overline{\mathrm{OE} 2}$ | $Q_{A}$ thru $Q_{H}$ | 2.7 | 5.6 | 8 | 2.2 | 10.5 | 2.7 | 9 | ns |
| tPZL |  |  | 3.2 | 6.6 | 10 | 2.7 | 12 | 3.2 | 11 |  |
| tPHZ | $\overline{\mathrm{OE} 1}$ or $\overline{\mathrm{OE} 2}$ | $Q_{A}$ thru $Q_{H}$ | 1.7 | 4.1 | 6 | 1.7 | 9 | 1.7 | 7 | ns |
| tPLZ |  |  | 1.2 | 3.6 | 5.5 | 1.2 | 7.5 | 1.2 | 6.5 |  |

$\dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## PARAMETER MEASUREMENT INFORMATION



NOTES: A. $C_{L}$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: $\mathrm{PRR} \leq 1 \mathrm{MHz}, \mathrm{Z}_{\mathrm{O}}=50 \Omega, \mathrm{t}_{\mathrm{r}} \leq 2.5 \mathrm{~ns}, \mathrm{t}_{\mathrm{f}} \leq 2.5 \mathrm{~ns}$, duty cycle $=50 \%$.
D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

| Orderable Device | Status <br> (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan <br> (2) | Lead finish/ Ball material <br> (6) | MSL Peak Temp <br> (3) | Op Temp ( ${ }^{\circ} \mathrm{C}$ ) | Device Marking <br> (4/5) | Samples |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN74F299DW | ACTIVE | SOIC | DW | 20 | 25 | RoHS \& Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | F299 | Samples |
| SN74F299DWR | ACTIVE | SOIC | DW | 20 | 2000 | RoHS \& Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | F299 | Samples |
| SN74F299N | ACTIVE | PDIP | N | 20 | 20 | RoHS \& Non-Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74F299N | Samples |

${ }^{(1)}$ The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.
${ }^{(2)}$ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed $0.1 \%$ by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: Tl defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement
${ }^{(3)}$ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
${ }^{(4)}$ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device
${ }^{(5)}$ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
${ }^{(6)}$ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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[^0]TeXAS

## TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package <br> Type | Package <br> Drawing | Pins | SPQ | Reel <br> Diameter <br> $(\mathbf{m m})$ | Reel <br> Width <br> $\mathbf{W 1}(\mathbf{m m})$ | A0 <br> $(\mathbf{m m})$ | B0 <br> $(\mathbf{m m})$ | K0 <br> $(\mathbf{m m})$ | P1 <br> $(\mathbf{m m})$ | W <br> $(\mathbf{m m})$ | Pin1 <br> Quadrant |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN74F299DWR | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |

PACKAGE MATERIALS INFORMATION


All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length $(\mathbf{m m})$ | Width $(\mathbf{m m})$ | Height $(\mathrm{mm})$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN74F299DWR | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |

## TUBE



B - Alignment groove width
*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T ( $\boldsymbol{\mu m}$ ) | B ( $\mathbf{m m}$ ) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN74F299DW | DW | SOIC | 20 | 25 | 507 | 12.83 | 5080 | 6.6 |
| SN74F299N | N | PDIP | 20 | 20 | 506 | 13.97 | 11230 | 4.32 |

N (R-PDIP-T**)
PLASTIC DUAL-IN-LINE PACKAGE
16 PINS SHOWN


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D The 20 pin end lead shoulder width is a vendor option, either half or full width.


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side
5. Reference JEDEC registration MS-013.


NOTES: (continued)
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.


SOLDER PASTE EXAMPLE BASED ON 0.125 mm THICK STENCIL

SCALE:6X

NOTES: (continued)
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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